Below a short summary from the 12th HWG Meeting.

A) Last TB analyses

- there was a talk by Jakub with his final results on the shower energy deposition
-- change of fitting from Gaussian to Landau&Gaussian resulted in systematically higher depositions and better agreement
with Itamar results and MC results

-- still there is systematic difference in comparison to MC for higher radiation lengths
-- MC need to take into account beam profile for precise comparison - Strahinja is working on it
- general conculsions:
a) we need to compare Itamar and Jakub results, and Veta whenever she will complete it, and compare it to the next, more precise MC analyses (we hope that all or most of it will happen before the next HWG Meeting)
b) we need to start (immediately) writing a note/paper. We will discuss it in following days with Aharon and send email to the Collaboration

B) Preparation of the next TB
- Jan and Sasha presented:
-- ideas about new bonding technology with laser soldering - interesting R&D for sensor, various details should be verified, may be done at CERN, possible future option but not for the next TB
-- Update on LumiCal Module assembly at TAU
 --- integration of sensor plus kapton plus panasonic connector is proceeding well
 --- another option for sensor bonding - TAB (Tape Automiatic Bonding) is studied. If successful, one of the sensor planes
could be done in this way even for the next TB (other planes will have standard wire-bonding)
- Tomasz Wojton presented cross-talk measurements of new (TAU) and old (INP) kapton cables
 -- for long strips the cross-talk is above 15%, which is very high value. It is not a problem for next TB, in fact it should be studied during next TB. But for longer-term future it is certainly too much.
- Sergej showed 2 slides with energy deposition obtained with/without tungsten plane before the 1st sensor plane
 -- the Landau peak is seen in the 1st plane even with tungsten plane before. In addition double&triple Landau peaks are seen - interesting to study. Finally, tungsten plane before sensor makes the setup safer.
 -- conclusion - it seems a good solution to have the tungsten before the 1st sensor plane

C) new readout board for the thin calorimeter (beyond next TB)
- Leszek presented possible architectures/block diagrams regarding placement of ASICs/FPGAs/DAQ
- although there are some pros/cons of various options, there is not yet enough progress/expertise to decide
about final architecture - we should continue discussions and try to work out the solution in the next few months
Last, we have agreed that the next HWG Meeting will be in 3 weeks on 28 of July at  4 pm (cern time).

Best Regards,
  marek